

FOR THE MEDIA

ASMPT Wins New Orders for Nineteen Chip-to-Substrate TCB Tools to Serve AI Chip Market

Singapore, 3 Dec 2025 – ASMPT (HKEX: 0522), the world's leading provider of integrated hardware and software solutions for semiconductor and electronics manufacturing, announced it had won new orders for 19 Chip-to-Substrate (C2S) TCB tools from a major OSAT partner of the leading foundry serving the AI chip market.

ASMPT is the sole supplier and Process of Record (POR) of C2S TCB solutions for this customer, supporting their high-volume manufacturing requirements. These latest systems will enable their next-generation C2S bonding for logic applications as compound die sizes get larger. This demonstrates the customer's continued confidence in ASMPT's technological leadership and production-proven capabilities. Looking ahead, ASMPT is well-positioned to secure additional orders in the future.

This continued momentum for ASMPT's flagship Thermo-Compression Bonding (TCB) solutions reinforces its position as the industry's leading provider of advanced packaging solutions for artificial intelligence and high-performance computing applications.

"The TCB market is experiencing transformational growth driven by AI and HPC applications," said **Robin Ng, Group CEO, ASMPT**. "Our comprehensive technology portfolio spanning chip-on-wafer, chip-on-substrate, and HBM applications positions ASMPT uniquely to support our customers' most demanding advanced packaging roadmaps. This latest win validates our technology leadership and highlights the market's recognition of our ability to deliver production-ready, scalable platforms."

With the largest TCB installed base worldwide consisting of more than 500 tools, ASMPT is strategically positioned to capture between 35% to 40% of an expanded TCB market. ASMPT recently expressed confidence that the TCB Total Addressable Market (TAM) projection will exceed US\$1 billion by 2027, bolstered by recent news about AI ecosystem investments.

About ASMPT Limited

ASMPT Limited is a leading global supplier of hardware and software solutions for the manufacture of semiconductors and electronics. Headquartered in Singapore, ASMPT's offerings encompass the semiconductor assembly & packaging, and SMT (surface mount technology) industries, ranging from wafer deposition to the various solutions that organise, assemble and package delicate electronic components into a vast range of end-user devices. ASMPT partners with customers very closely, with continuous investment in R&D helping to provide cost-effective, industry-shaping solutions that achieve higher productivity, greater reliability, and enhanced quality.

ASMPT is listed on the Stock Exchange of Hong Kong (HKEX stock code: 0522) and is one of the constituent stocks of the Hang Seng Composite MidCap Index under the Hang Seng Composite Size Indexes, the Hang Seng Composite Information Technology Industry Index under Hang Seng Composite Industry Indexes, the Hang Seng Corporate Sustainability Benchmark Index, and the Hang Seng HK 35 Index. To learn more about ASMPT, please visit us at www.asmpt.com.

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